

CYM1840

Features

- High-density 8-megabit SRAM module
- High-speed CMOS SRAMs — Access time of 20 ns
- Independent byte and word controls
- · Low active power
 - 6.2W (max.)
- SMD technology
- · TTL-compatible inputs and outputs
- Low profile
 - Max. height of .350 in.
- Small PCB footprint
 - —1.8 sq. in.

Functional Description

The CYM1840 is a high-performance 8-megabit static RAM module organized as 256K words by 32 bits. This module is

256K x 32 Static RAM Module

constructed from eight 256K x 4 SRAMs in SOJ packages mounted on an epoxy laminate substrate with pins. Four chip selects (\overline{CS}_0 , \overline{CS}_1 , \overline{CS}_2 , and \overline{CS}_3) are used to independently enable the four bytes. Two write enables (\overline{WE}_0 and \overline{WE}_1) are used to independently write to either the upper or lower 16-bit word of RAM. Reading or writing can be executed on individual bytes or on any combination of multiple bytes through the proper use of selects and write enables.

Writing to each byte is accomplished when the appropriate chip select (CS) and write enable (WE) inputs are both LOW. Data on the input/output pins $(\overline{I/O}_X)$ is written into the memory location specified on the address pins (A_0 through A_{17}).

Reading the device is accomplished by taking the chip selects (CS) LOW, while write enables (WE) remain HIGH. Under these conditions the contents of the memory location specified on the address pins will appear on the data input/output pins (<u>I/O</u>).

The data input/output pins stay in the high-impedance state when write enables (WE) are LOW or the appropriate chip selects are HIGH.



Selection Guide

	1840-20	1840-25	1840-30	1840-35	1840-45	1840-55
Maximum Access Time (ns)	20	25	30	35	45	55
Maximum Operating Current (mA)	1120	1120	1120	1120	1120	1120
Maximum Standby Current (mA)	320	320	320	320	320	320

Cypress Semiconductor Corporation

3901 North First Street

San Jose CA 95134

408-943-2600 October 1990 - Revised June 1993



Maximum Ratings

(Above which the useful life may be impaired. For user guidelines, not tested.)

Storage Temperature-65°C to +150°C Ambient Temperature with Power Applied (PD)--10°C to +85°C DC Voltage Applied to Outputs in High Z State.....-0.5V to +7.0V DC Input Voltage-3.0V to +7.0V

Operating Range

Range	Ambient Temperature	v _{cc}
Commercial	0°C to +70°C	5V ± 10%

lectrical Characteristics Over the Operating Range

			CYM1840		
Parameter	Description	Test Conditions	Min.	Max.	Unit
V _{OH}	Output HIGH Voltage	V_{CC} = Min., I_{OH} = -4.0 mA	2.4		V
V _{OL}	Output LOW Voltage	V _{CC} = Min., I _{OL} = 8.0 mA		0.4	V
V _{IH}	Input HIGH Voltage		2.2	V _{CC}	V
V _{IL}	Input LOW Voltage		-0.5	0.8	V
I _{IX}	Input Load Current	$GND \leq V_{I} \leq V_{CC}$	-20	+20	μA
I _{OZ}	Output Leakage Current	$GND \leq V_O \leq V_{CC}$, Output Disabled	-50	+50	μΑ
I _{CC}	V _{CC} Operating Supply Current	$V_{CC} = Max., I_{OUT} = 0 \text{ mA}, \overline{CS}_X \le V_{IL}$		1120	mA
I _{SB1}	Automatic CS Power-Down Current ^[1]	Max. V_{CC} , $\overline{CS}_X \ge V_{IH}$, Min. Duty Cycle = 100%		320	mA
I _{SB2}	Automatic CS Power-Down Current ^[1]	Max. V _{CC} , $\overline{CS}_X \ge V_{CC}$ - 0.3V, V _{IN} ≥ V _{CC} - 0.3V or V _{IN} ≤ 0.3V		160	mA

Capacitance^[2]

Parameter	Description	Test Conditions	Max.	Unit
C _{INA}	Input Capacitance, Address Pins	$T_A = 25^{\circ}C, f = 1 \text{ MHz},$	100	pF
C _{INB}	Input Capacitance, I/O Pins	$V_{CC} = 5.0V$	30	pF
C _{OUT}	Output Capacitance		30	pF

Notes:

A pull-up resistor to V_{CC} on the CS input is required to keep the device deselected during V_{CC} power-up, otherwise I_{SB} will exceed values given. Tested initially and after any design or process changes that may affect these parameters. 1.

2.

AC Test Loads and Waveforms





Switching Characteristics Over the Operating Range^[3]

		1840-20		184	0-25	184	0-30	
Parameter	Description	Min.	Min. Max.		Max.	Min.	Max.	Unit
READ CYCLE	•		•					
t _{RC}	Read Cycle Time	20		25		30		ns
t _{AA}	Address to Data Valid		20		25		30	ns
t _{OHA}	Output Hold from Address Change	5		5		5		ns
t _{ACS}	CS LOW to Data Valid		20		25		30	ns
t _{LZCS}	CS LOW to Low Z ^[4]	5		5		5		ns
t _{HZCS}	CS HIGH to High Z ^[4, 5]		20		20		20	ns
t _{PU}	CS LOW to Power-Up	0		0		0		ns
t _{PD}	CS HIGH to Power-Down		20		25		30	ns
WRITE CYCLE	6]		•	•		•		
t _{WC}	Write Cycle Time	20		25		30		ns
t _{SCS}	CS LOW to Write End	18		20		25		ns
t _{AW}	Address Set-Up to Write End	18		20		25		ns
t _{HA}	Address Hold from Write End	2		2		2		ns
t _{SA}	Address Set-Up to Write Start	2		2		2		ns
t _{PWE}	WE Pulse Width	15		20		25		ns
t _{SD}	Data Set-Up to Write End	13		15		15		ns
t _{HD}	Data Hold from Write End	2		2		2		ns
t _{LZWE}	WE HIGH to Low Z	0		0		0		ns
t _{HZWE}	WE LOW to High Z ^[5]	0	15	0	15	0	15	ns

Notes:

Test conditions assume signal transition times of 5 ns or less, timing reference levels of 1.5V, input pulse levels of 0 to 3.0V, and output loading of the specified I_{OL}/I_{OH} and 30-pF load capacitance. At any given temperature and voltage condition, t_{HZCS} is less than t_{LZCS} for any given device. t_{HZCS} and t_{HZWE} are specified with $C_L = 5$ pF as in part (b) of AC Test Loads and Waveforms. Transition is measured ±500 mV from steady-state voltage. The internal write time of the memory is defined by the overlap of CS LOW and WE LOW. Both signals must be LOW to initiate a write and either signal can terminate a write by going HIGH. The data input set-up and hold timing should be referenced to the rising edge of the signal that terminates the write. 3.

4.

5.

6.



Switching	Characteristics	Over the Op	perating R	ange ^[3] (continued)
-----------	------------------------	-------------	------------	-----------------------	------------

		1840-35		184	0-45	184	0-55	
Parameter	Description	Min.	Min. Max.		Max.	Min.	Max.	Unit
READ CYCLE								•
t _{RC}	Read Cycle Time	35		45		55		ns
t _{AA}	Address to Data Valid		35		45		55	ns
t _{OHA}	Output Hold from Address Change	5		5		5		ns
t _{ACS}	CS LOW to Data Valid		35		45		55	ns
t _{LZCS}	CS LOW to Low Z ^[4]	5		5		5		ns
t _{HZCS}	CS HIGH to High Z ^[4,5]		25		25		25	ns
t _{PU}	CS LOW to Power-Up	0		0		0		ns
t _{PD}	CS HIGH to Power-Down		35		45		55	ns
WRITE CYCLE	6]							•
t _{WC}	Write Cycle Time	35		45		55		ns
t _{SCS}	CS LOW to Write End	30		40		50		ns
t _{AW}	Address Set-Up to Write End	30		40		50		ns
t _{HA}	Address Hold from Write End	6		6		6		ns
t _{SA}	Address Set-Up to Write Start	6		6		6		ns
t _{PWE}	WE Pulse Width	25		30		40		ns
t _{SD}	Data Set-Up to Write End	25		30		35		ns
t _{HD}	Data Hold from Write End	6		6		6		ns
t _{LZWE}	WE HIGH to Low Z	0		0		0		ns
t _{HZWE}	WE LOW to High Z ^[5]	0	25	0	25	0	25	ns

Switching Waveforms





Switching Waveforms (continued)









Switching Waveforms (continued)



Notes:

7.

8. 9.

Device is continuously selected, $\overline{CS} = V_{IL}$. \overline{WE} is HIGH for read cycle. If \overline{CS} goes HIGH simultaneously with \overline{WE} HIGH, the output remains in a high-impedance state.

Truth Table

CS	WE	Input/Output	Mode
Н	Х	High Z	Deselect/Power-Down
L	Н	Data Out	Read
L	Ĺ	Data In	Write

Ordering Information

Speed	Ordering Code	Package Name	Package Type	Operating Range
20	CYM1840PD-20C	PD06	60-Pin DIP Module	Commercial
25	CYM1840PD-25C	PD06	60-Pin DIP Module	Commercial
30	CYM1840PD-30C	PD06	60-Pin DIP Module	Commercial
35	CYM1840PD-35C	PD06	60-Pin DIP Module	Commercial
45	CYM1840PD-45C	PD06	60-Pin DIP Module	Commercial
55	CYM1840PD-55C	PD06	60-Pin DIP Module	Commercial

Document #: 38-M-00040-B



←.300/.350

.600TYP.

Package Diagram

60-Pin DIP Module PD06



© Cypress Semiconductor Corporation, 1993. The information contained herein is subject to change without notice. Cypress Semiconductor Corporation assumes no responsibility for the use of any circuitry other than circuitry embodied in a Cypress Semiconductor product. Nor does it convey or imply any license under patent or other rights. Cypress Semiconductor does not authorize its products for use as critical components in life-support systems where a malfunction or failure may reasonably be expected to result in significant injury to the user. The inclusion of Cypress Semiconductor products in life-support systems where a malfunction or failure may reasonably be expected to result in significant injury to the user. The inclusion of charges.